

Publications - Dr. Ken Gilleo (partial - article list) approx. 1/2008 update

BOOKS

Chapter author, **The Future of Technology - 50 Years Ahead**"; IPC 50th Anniversary Book, **From Vacuum Tubes to Nanotubes**, February 2007.

Chapter author, **The History of Printed Circuits; IPC 50th Anniversary Book, From Vacuum Tubes to Nanotubes**, February 2007.

Author, **MEMS/MOEMS Packaging**, McGraw-Hill, NY, published July 2005.

Author, "**Industrial Forensics – Strategic Approach to Problem Solving**", Web download at www.ET-Trends.com, 2007.

Editor/Author, **Area Array Packaging Concepts and Designs**, McGraw-Hill, NY, published November 2003

Editor/Author, **Area Array Packaging Materials**, McGraw-Hill, NY, published November 2003

Editor/Author, **Area Array Packaging Processes and Equipment**, McGraw-Hill, NY, published November 2003

Author/Chapter: "Flip Chips", **Chip-Scale Packaging for Modern Electronics**, J. Fjelstad, R. Ghaffarian, Y. Kim, Electrochemical Publications, LTD, Isle of Man, 2003

Author/Chapter: "Photonics", **Science & Technology Yearbook 2002**, McGraw-Hill, NY 2002

Author/Chapter: "Printed Circuit History and Overview", C. Harper, **Electronic Assembly Fabrication**, McGraw-Hill, NY, 2002

Editor/Author, "**Area Array Packaging Handbook**", McGraw-Hill, NY, Nov. 2001

Author/Chapter: "Conductive Adhesives as a Lead-Free Alternative", Hwang, J., **Environmentally-Friendly Electronics: Lead-Free Technology**, Electrochemical Publications, London, 2001

Coauthor: **Surface Mount Technology Basics**, Seimens, Munich, Germany, 2001

Author/Chapter: "Flip Chip Technology: Materials, and Processes for Next Generation of High-Performance Electronics", **Electronic Packaging and Interconnect Handbook**, McGraw-Hill, NY, 2000

Author/Chapter: "Introduction to Conductive Adhesives", **Conductive Adhesives for Electronics**, J. Lu, Electrochemical Publishers Ltd. UK, 2000

Author, **Handbook of Polymer Thick Film** - Environmentally Conscious Manufacturing, Van Nostrand Reinhold, NY, May 1, 1995

Author/Chapter: "Surface Tension and Rheology", **Handbook of Coating Technology**, Marcel-Dekker, NY 1991

Editor/Author, **Handbook of Flexible Circuits**, Van Nostrand Reinhold, NY, 1992

Author/Chapter: "Screen Printing", **Plastic Finishing and Decorating**, pp. 152-172, Van Nostrand Reinhold, NY, 1986

Author/Chapter: "Nylon Flammability", **Advances in Flame Retardants**, Vol. 5, pp. 165-181, 1975

Patents (33 US published) are listed in separate document.

PAPERS & Presentations

2008

"Big Nano Success Stories", CircuiTree Magazine, August 2008.

"Flex Circuit Applications", Workshop, APEX Designers Summit, March 31, 2008, Mandalay Convention Center, Las Vegas, NV.

"MEMS, MOEMS and Nano - Devices and Packaging" Workshop, APEX Designers Summit, March 31, 2008, Mandalay Convention Center, Las Vegas, NV.

"Area Array Packaging - Then and Now", CircuiTree Magazine, March 2008.

"Past, Present, and Future of Flexible Circuitry", IPC International Conference on Flexible Circuits, February 13, 2008, Phoenix, AZ.

"Flex Circuit Fundamentals", Workshop, IPC International Conference on Flexible Circuits, February 13, 2008, Phoenix, AZ.

"Flex Circuitry Applications - From Inner Space to Outer Space", IPC International Conference on Flexible Circuits, February 13, 2008, Phoenix, AZ.

"Chip Packaging 2.0 Provides Benefits to Board Designers", Martin Hart and Ken Gilleo, feature article, CircuiTree Magazine, February 2008.

“Fuels of the Future”, podcast, CircuiTree Magazine, posted January 28, 2008.

2007

Monthly Newsletters/Reports for 2007 - over 50 reports: “Electronics”, “Energy”, “RFID”, “Printed Electronics”, “Flat Panel Displays”, and “Semiconductors”. These reports cover the latest events on the topics and range in length to about 4 to 15-pages. They can be downloaded at <http://www.et-trends.com/downloads/downloads.html>

“Making a Small Impression”, CircuiTree Magazine, December 2007.

“PCBs, Semiconductors and Nanotechnology”, CircuiTree Magazine, September 2007

“Nature Loves Paradigm Shifts”, presented at International Wafer Level Packaging Conference, September 17-20, 2007, San Jose, CA

“The 3D End Game”, presented at International Wafer Level Packaging Conference, September 17-20, 2007, San Jose, CA.

“MEMS, MOEMS and Nanotechnology Overview”, Workshop, presented at International Wafer Level Packaging Conference, September 17, 2007, San Jose, CA

“MEMS and MOEMS Packaging”, Workshop, presented at International Wafer Level Packaging Conference, September 17, 2007, San Jose, CA

“The First 105 Years of Flexible Circuitry, Keynote Presentation, IPC Flex Conference on Flexible Circuitry, June 13, 2007 in Minneapolis, MN. Published as IPC CD, but also published in CircuiTree with link to www.ET-Trends.com

“Flex Circuitry Basics”, Workshop, IPC Flex Conference on Flexible Circuitry, June 12, 2007 in Minneapolis, MN.

“Flex Circuit Applications”, IPC Flex Conference on Flexible Circuitry, June 12, 2007 in Minneapolis, MN.

“Today’s Movie—Stacking Silicon: The Race to TSV, in 3D”, CircuiTree, June 2007.

“The Real Printed Electronics”, CircuiTree Magazine, March 2007.

“Interview with Dr. Ken Gilleo”, Movers & Shakers column, Semiconductor International, February 2, 2007.

“Future Tech”, Pan Pacific Conference, SMTA Proceedings, January 30 - February 1, 2007.

“MEMS: Beyond Borrowed Packaging”, interview of Ken Gilleo, Semiconductor International, January 1, 2007

2006

“The Enlightened Chip”, CuircuiTree, p. 28, December 2006.

“The Future of Packaging”, CuircuiTree, p. 56 - 59, December 2006.

“Vertical Thinking”, CircuiTree Magazine, September 2006.

“Interview with Ken Gilleo - MEMS packaging: history and current trends”, MEMS, Investor Journal, August 04, 2006; <http://www.memsinvestorjournal.com/>

“Step 5 - Dispensable Electronic Materials”, Webcast, Advanced Packaging Magazine, March 9, 2006.

“The Alchemy of Nanotechnology”, CuircuiTree, February 2006.

“Nanotechnology, MST, MEMS, and MOEMS - Key Technologies of the 21st Century” T-01 TUTORIAL, APEX - IPC Printed Circuits Expo, Workbook, February 6, 2006, Anaheim, CA.

“Flexible Circuitry Advances: Materials, Processes & Constructions” W-26 Workshop, APEX - IPC Printed Circuits Expo, Workbook, February 7, 2006, Anaheim, CA.

“Thermoplastic Electronic Packaging: Low Cost – High Versatility”, APEX - IPC Printed Circuits Expo, pp. SO-6, 1-14, February, 8, 2006, Anaheim, CA.

“The New Convergence - Bio, Nano, and MEMS, p.32, February 2006, Circuits Assembly.

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“The Future is Plastics”, with D. Jones, CircuiTree Magazine, August 2006.

2005

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“Brainstorming New Package Ideas”, Panel Presentation/Discussion, November 3-4, International Wafer-Level Packaging Conference, San Jose, CA.

“The Future – the Next 50 Years”, SMTA Vendor Day, Milwaukee, WI, Oct. 18, 2005

“An All-Silicon Package?”, Circuits Assembly, p. 18, October 2005.

“Future Workshop”, SMTA International, Chicago, IL, September 29, 2005

“MEMS Packaging Update”, pp. 20, 22, Advanced Packaging, September 2005.

“MEMS in Medicine”, Circuits Assembly, August 2005.

“MEMS in Medicine”, SMTA Medical Electronics Conference, Minneapolis, MN, April 2005.

“Conductors”, CircuiTree, June 2005.

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“Super Synergy = Flex, Chips and RF Connections”, Keynote Address, IPC International Conference on Flexible Circuits & Chip Scale Packaging, June 22-23 2005, Minneapolis, MN.

“Flex Circuitry Applications from Advanced Packaging to Outer Space”, workshop, IPC International Conference on Flexible Circuits & Chip Scale Packaging, June 22-23 2005, Minneapolis, MN.

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“MEMS in Medicine”, Medical Electronic Conference, April 25-28, Minneapolis, MN.

“Bumping Technology”, Live Broadcast, Design Expo, March 16, 2005.

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Gilleo, K. et al, “Thermoplastic Injection Molding: New Packages and 3D Circuits”, IPC Printed Circuits Expo, February 20-23 2005, Anaheim, CA.

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2004

“The Circuit War”, CircuiTree magazine, December 2004.

“Could Technology Win World War III?”, Circuits Assembly, Vol. 15, November 2004.

“Emerging Technology”, SMTA – Hennepin Tech MN. November 10, 2004.

“Encapsulation: Materials, Processes and Equipment”, Advanced Packaging, p 38, 40, 42, October 2004.

“Introduction to Circuitry Materials”, TBA Live, San Jose, CA, October 19, 2004.

“The Time is Right for Injection Molded Packages”, SMTA International, September 27, 2004, Chicago, IL.

“Home Grown Circuits”, CircuiTree, p 26, September 2004.

“The World in Your Hand” Circuits Assembly, Vol. 15, July 2004.

Gilleo, K. et al “Low Ball BGA: A New Concept in Thermoplastic Packaging”, Semicon West, July 2004.

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“Time to Bring Back 3D Molded Circuits? CircuiTree, p 22, Sept. 2003.

“The Most Important Emerging Technology”, Circuits Assembly, August 2003.

“Exploring the Nanoworld”, Circuits Assembly, Vol. 14, August 2003.

“Can ET Pull Us Upward?”, SMTA Meeting/Nepcon East, Boston, MA, June 11, 2003.

“What’s Tomorrow’s Technology?”, Nepcon East, Boston, MA, June 2003.

“The 5 Most Important Emerging Technologies”, Panel Presentation, Nepcon East, Boston, MA, June 10, 2003

“Invention of Circuitry and the German Heritage”, Redaktion Elektronik, Germany, pp. 55 – 66, 29 June 2003.

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“The Other Circuit Process”, CircuiTree, p 32, June 2003.

“Get the Lead In! Getting the Lead In?”, CircuiTree, May 2003.

“Plastic Hermetic Packages for MEMS”, IMAPS New England 30th Annual Symposium, May 8, 2003, Boxboro, MA.

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“Chemists in Electronics”, Microelectronics in New England, Vol. XXVI No.1, May 2003.

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“Conductive Adhesives” - Workshop, APEX Conference, March 30, 2003, Anaheim, CA.

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“The Great Nanofoax?” EP&P, February 2003.

“Can ET Pull Us Up?” Pan Pacific Microelectronics Symposium, February 18 – 20, 2003, Kohala Coast, HI.

“ET Upward”, Invited Lecture, February 14, 2003, Worcester Polytechnic Institute, Worcester, MA.

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2002

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“Interposer Multilayer Circuitry”, CircuiTree, November 2002

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“MEMS and Telecommunications”, Ericsson Sponsor, October 11, 2002, Molndal, Sweden.

“RF-MEMS Tutorial”, IMEGO, October 10, 2002, Gothenburg, Sweden.

“MEMS Seminar”, Chalmers University, October 10, 2002, Kemivagen, Sweden.

“A Century of Chemists Crafting Circuits”, Microelectronics in New England (IMAPS), Vol. XXV, No. 3, Winter 2002.

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“Metalworking in the 21st Century”, EP&P, October 2002.

“MEMS and the Military”, SAAB-Bofors Sponsor, October 8, 2002, Karlskoga, Sweden.

“Flip Chip and Underfill” as thesis opponent, Orebro University, October 7, 2002, Orebro, Sweden.

“MEMS and Emerging Technology”, Invited Lecturer, October 6, 2002, Uppsala, University, Stockholm, Sweden.

“147 Year History of Optoelectronics”, October 1, 2002, IMAPS Nordic, Stockholm, Sweden.

“MEMS and RF Tutorial”, September 30, 2002, IMAPS Nordic, Stockholm, Sweden.

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K. Gilleo, J. Murray, Chapter 1 Circuit Patterning “The History of PCB Technology”, PC Fab, pp 18-20, 22, March 2000.

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